



**Efficient 400-800V Charging & Conversion with
GaNFast™ Power ICs &
GeneSiC™ Trench-Assisted Planar-Gate MOSFETs**

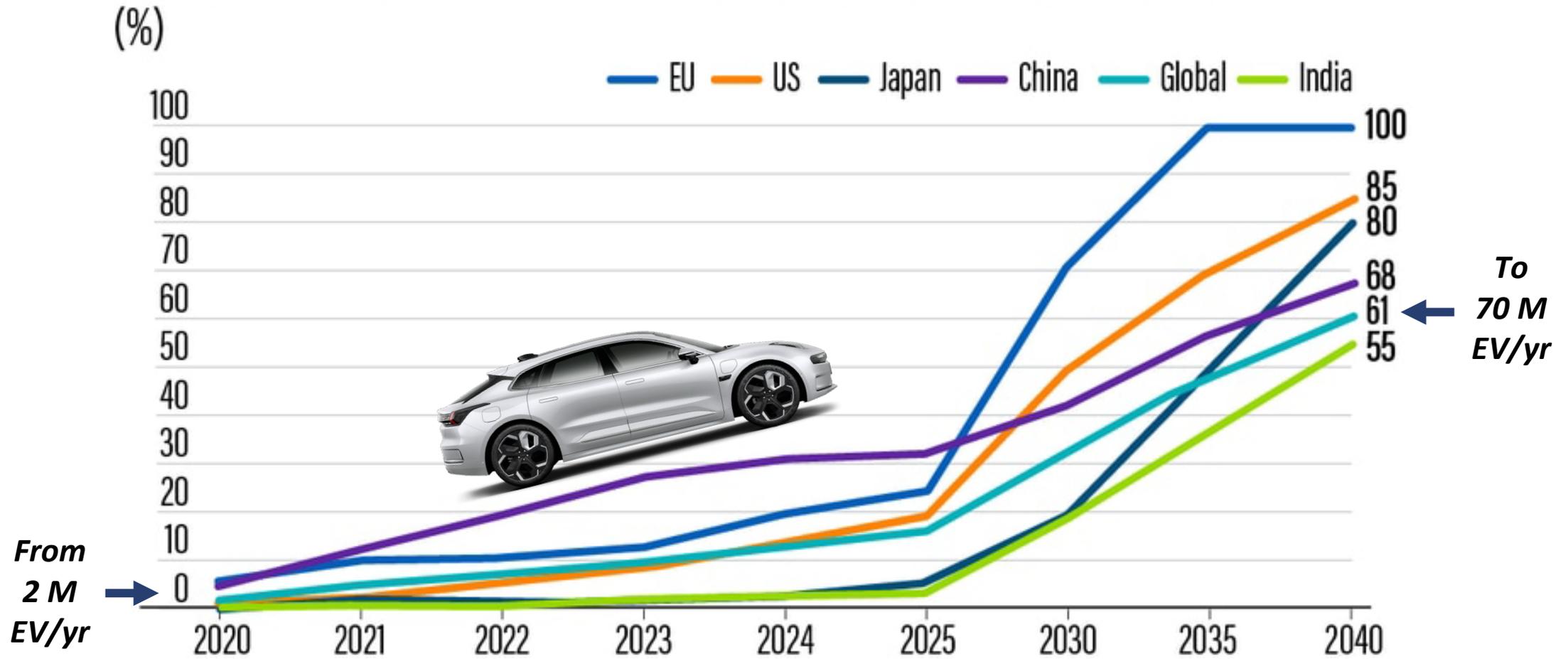


Dan Kinzer
COO/CTO, Co-Founder
March 28th, 2023

Navitas
Energy • Efficiency • Sustainability

The Navitas logo, a stylized white 'N' inside a circle, is positioned to the left of the company name. The tagline is written in a smaller, italicized font below the name.

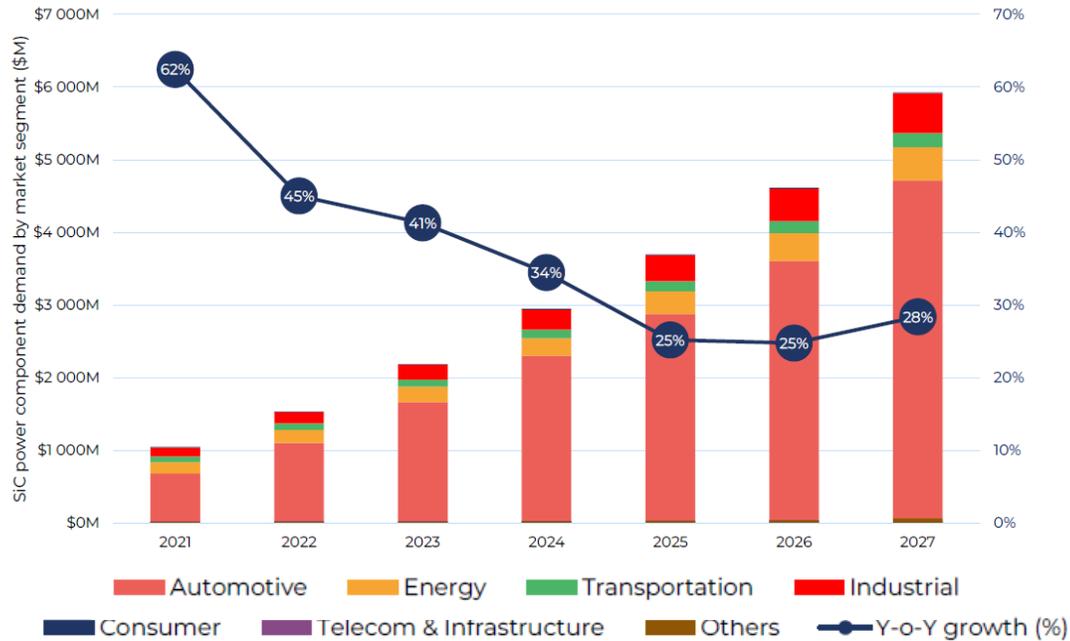
The Rise of EV



Source: IHS, Global Insight, Goldman Sachs Research, <https://www.thenationalnews.com/business/economy/2023/02/13/electric-vehicles-to-account-for-half-of-global-car-sales-by-2035-amid-net-zero-push/>

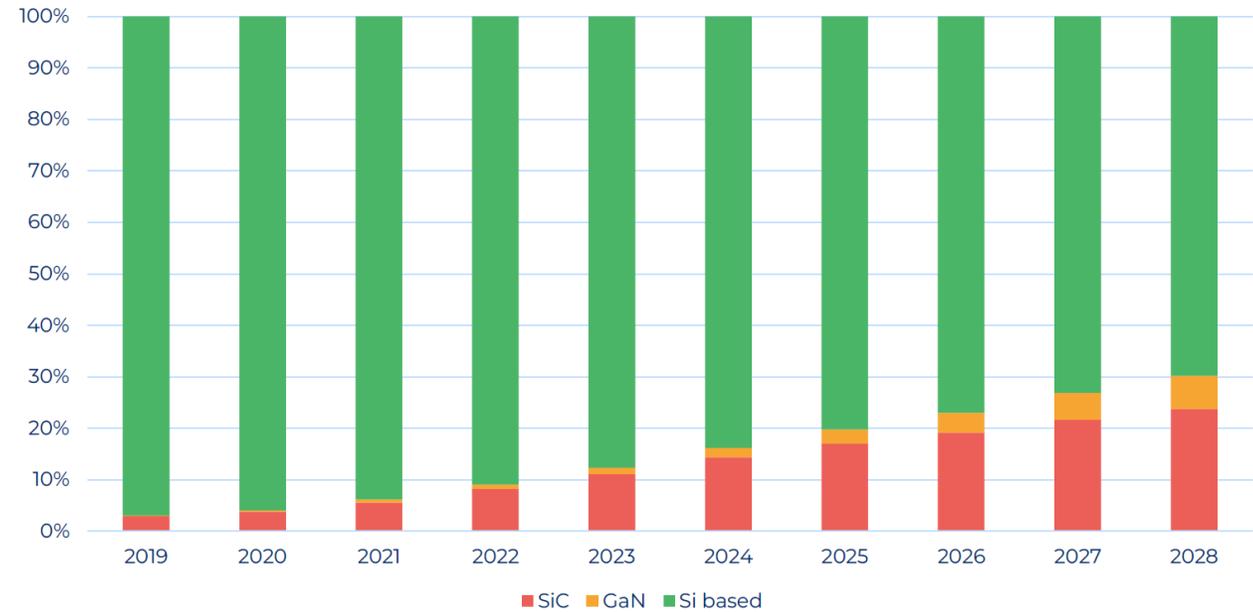
The Rise of EV = The Rise in WBG

SiC Revenue Forecast
(Yole, Nov'22)



SiC EV ~\$4.6B/yr by 2027

SiC+GaN Share of Market
(Yole, March'22)



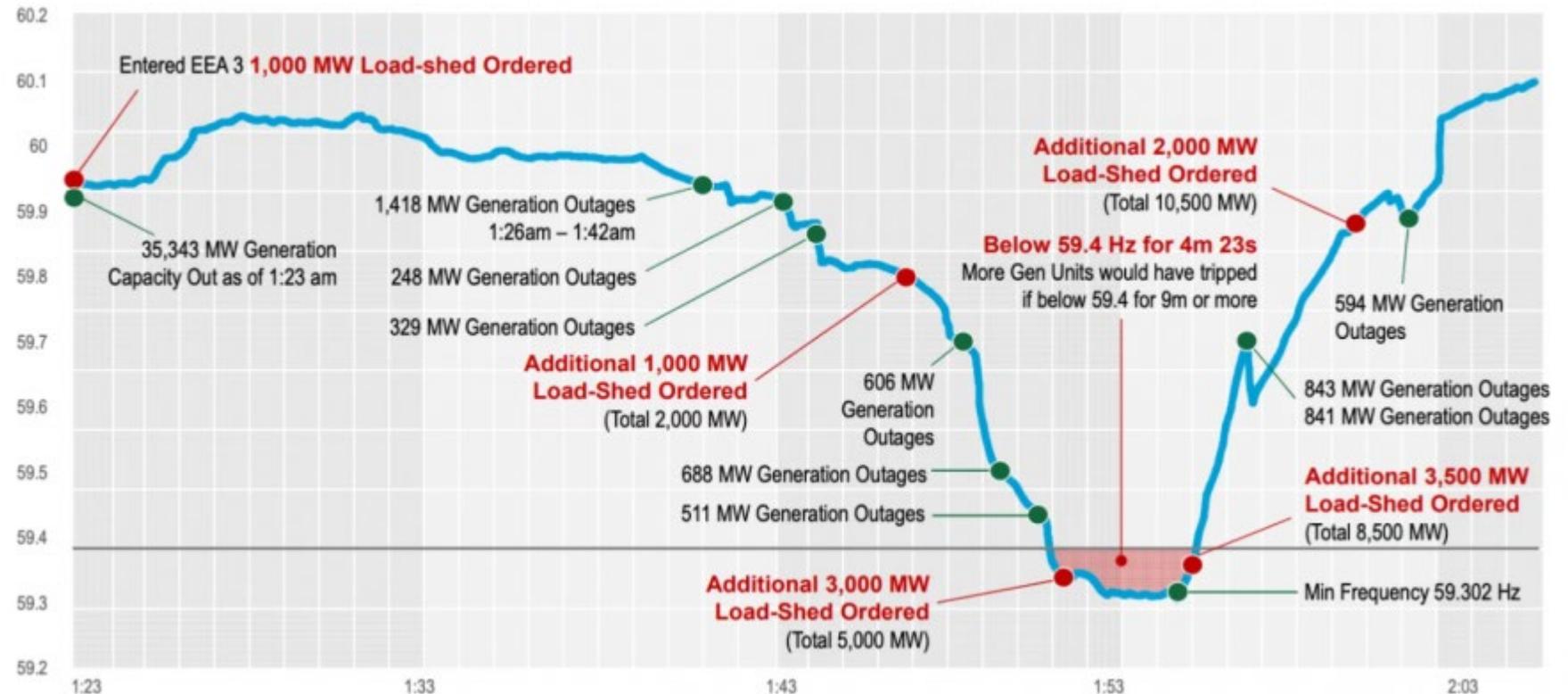
SiC+GaN ~30% by 2028



Life Can Be Unpredictable.



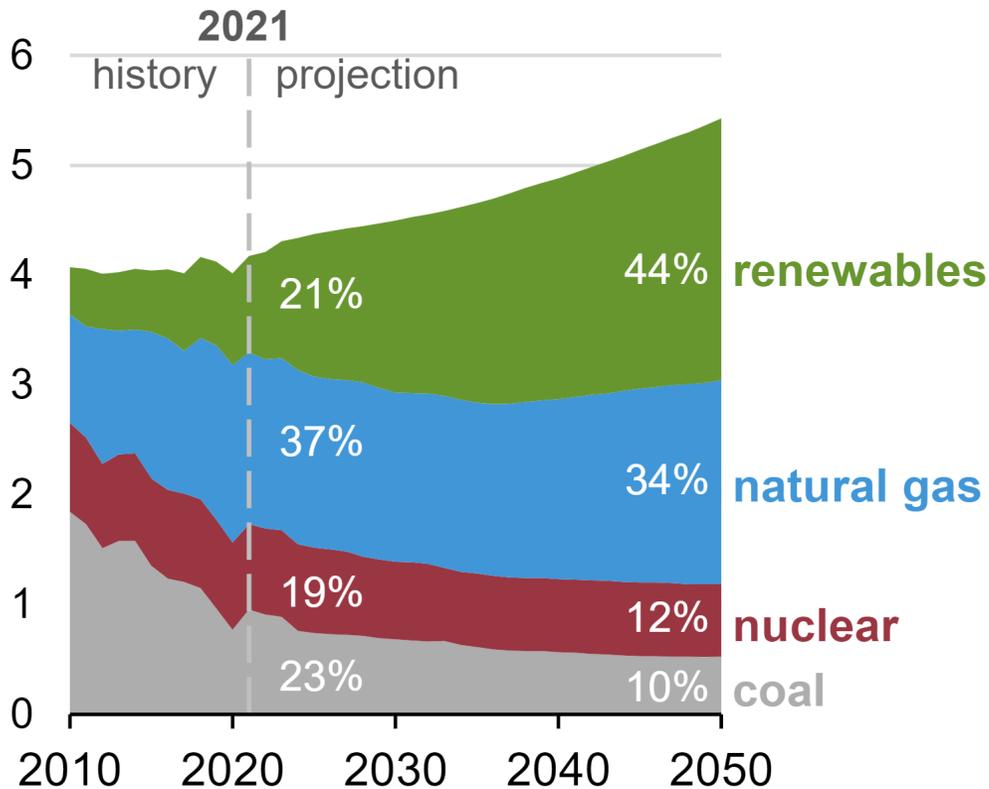
Texas Power Grid, February 21st 2021



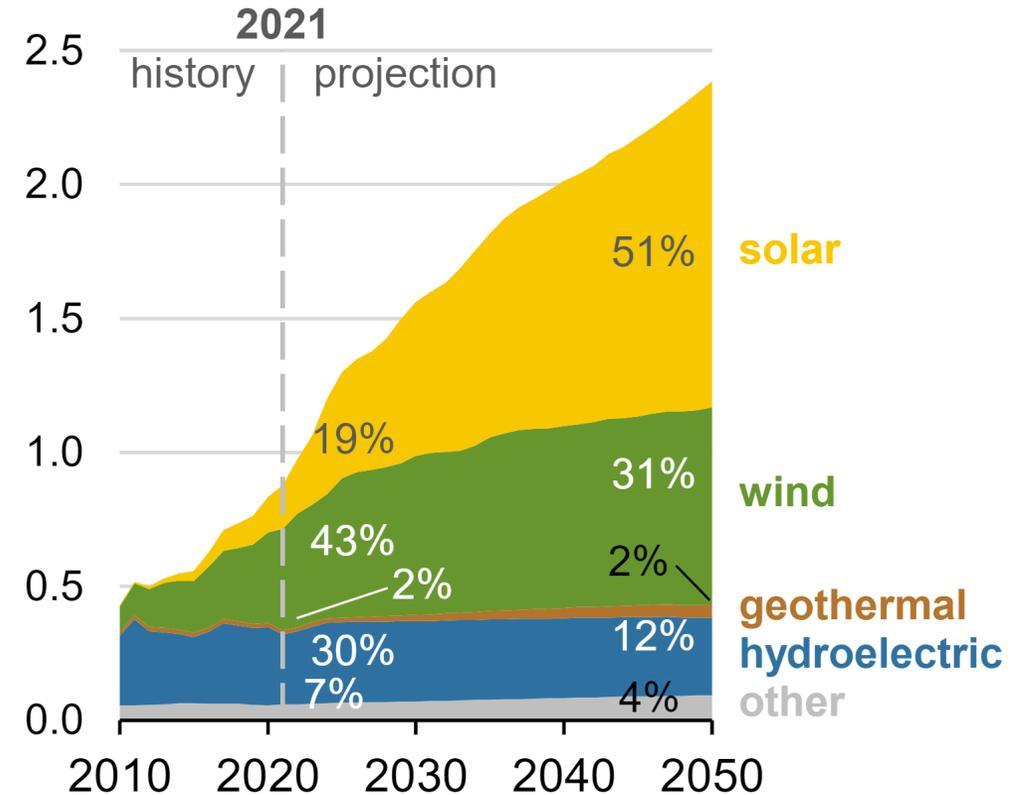
Electric Reliability Corporation of Texas (ERCOT)
December 2022, [link](#)

...and though Solar is a Growing Source of Power

**U.S. electricity generation
AEO2022 Reference case**
trillion kilowatthours



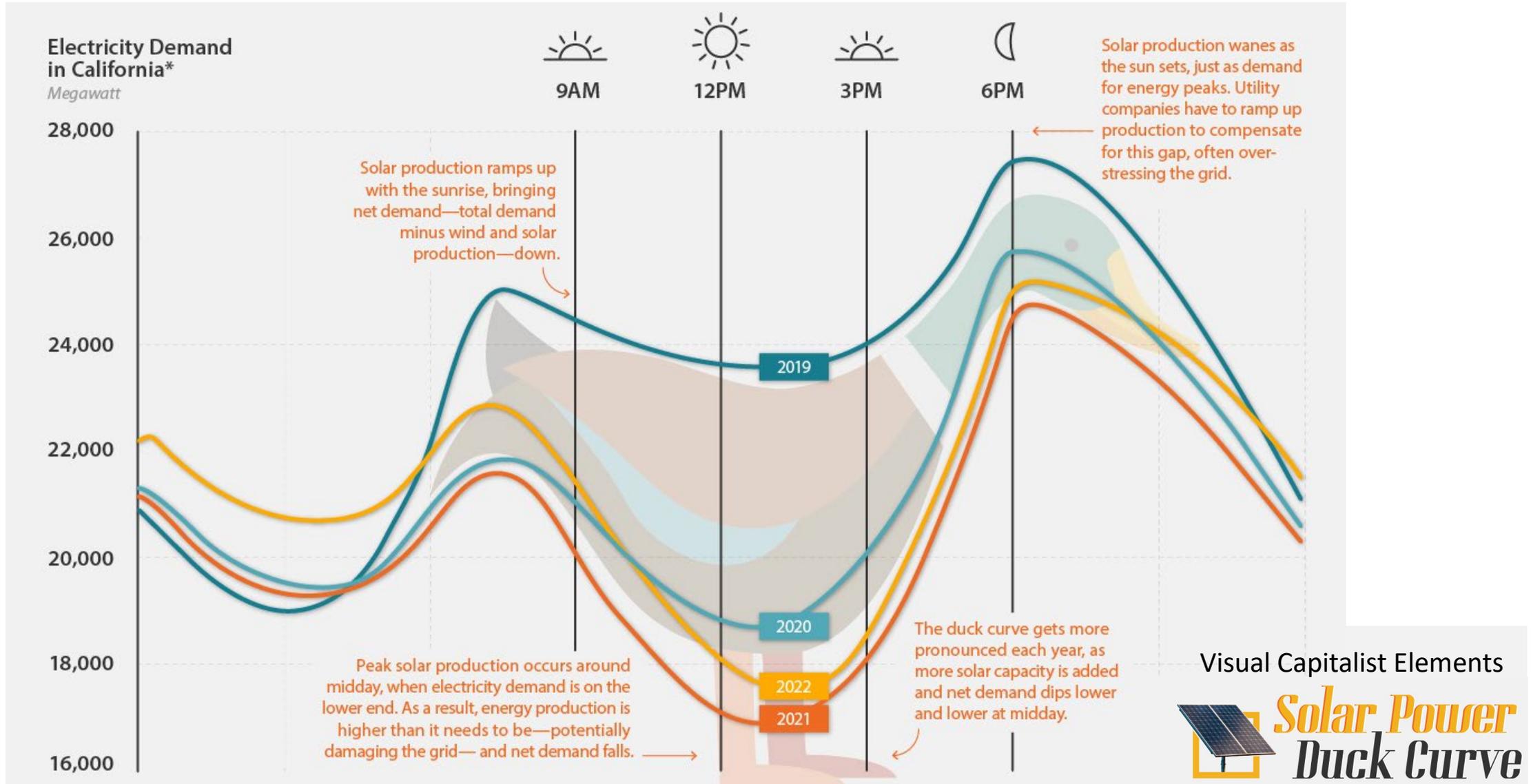
**U.S. renewable electricity generation
including end use**
trillion kilowatthours



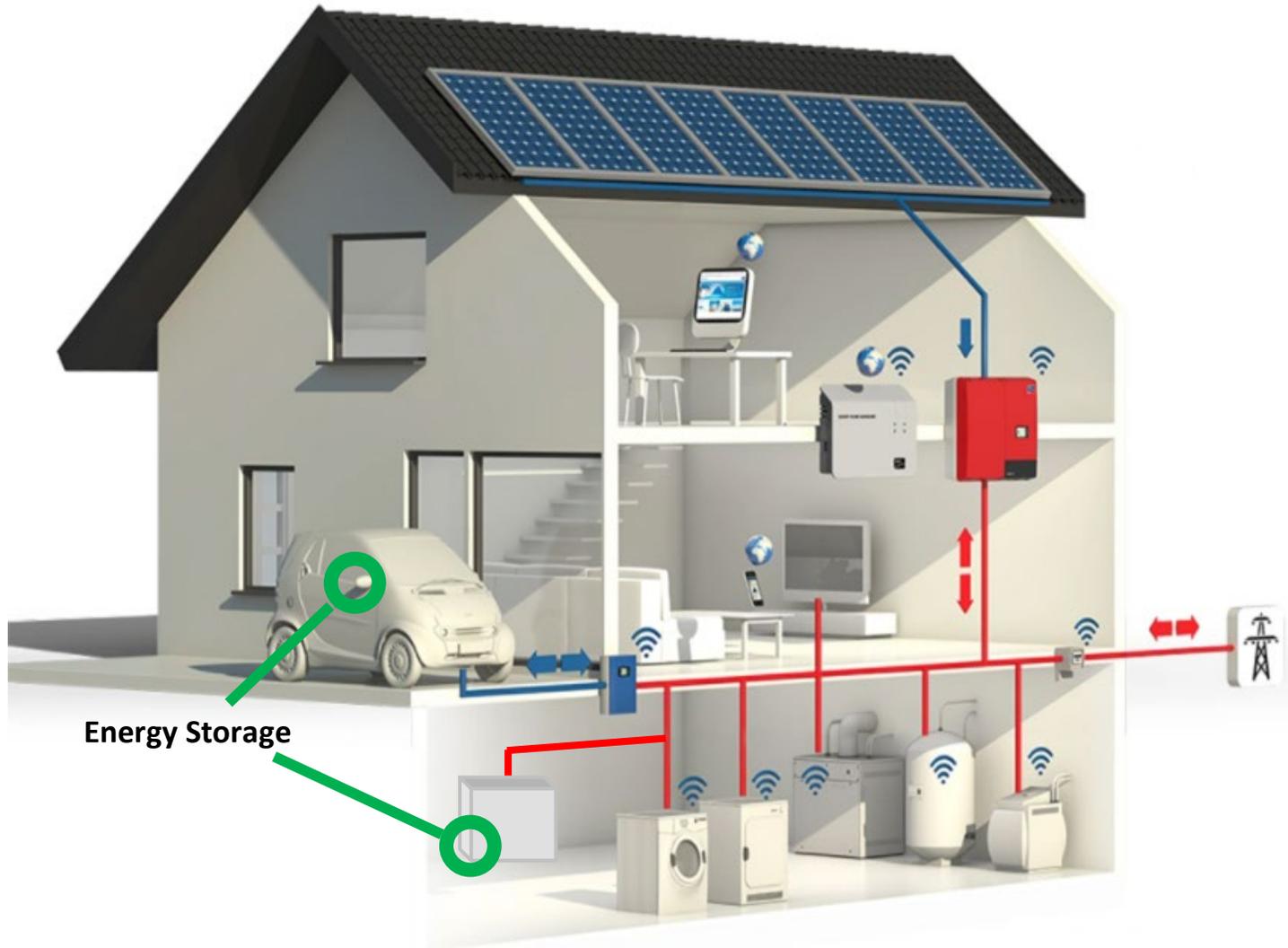
Source: U.S. Energy Information Administration, *Annual Energy Outlook 2022* (AEO2022)

Note: Biofuels are both shown separately and are included in petroleum and other liquids.

...Supply & Demand Don't Match



Domestic Micro-Grid with Energy Storage(s)



Battery Energy Storage System (BESS)

US storage/panel 'attach rate'
+1.8x in 18 months

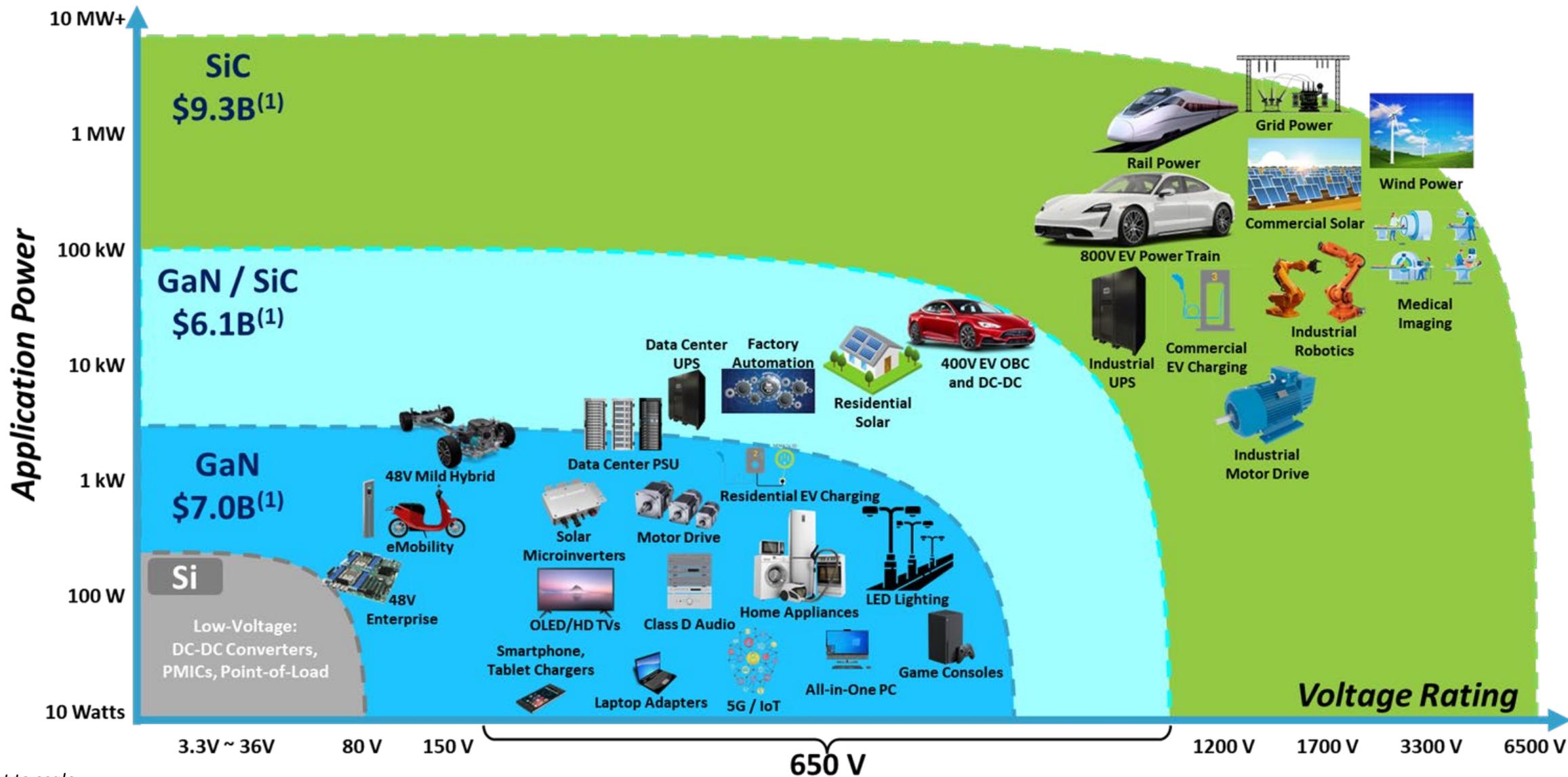
Energy storage available from

- Enphase
- Tesla
- Solaredge
- Toshiba
- GE, etc.

Bi-directional on-board chargers in:

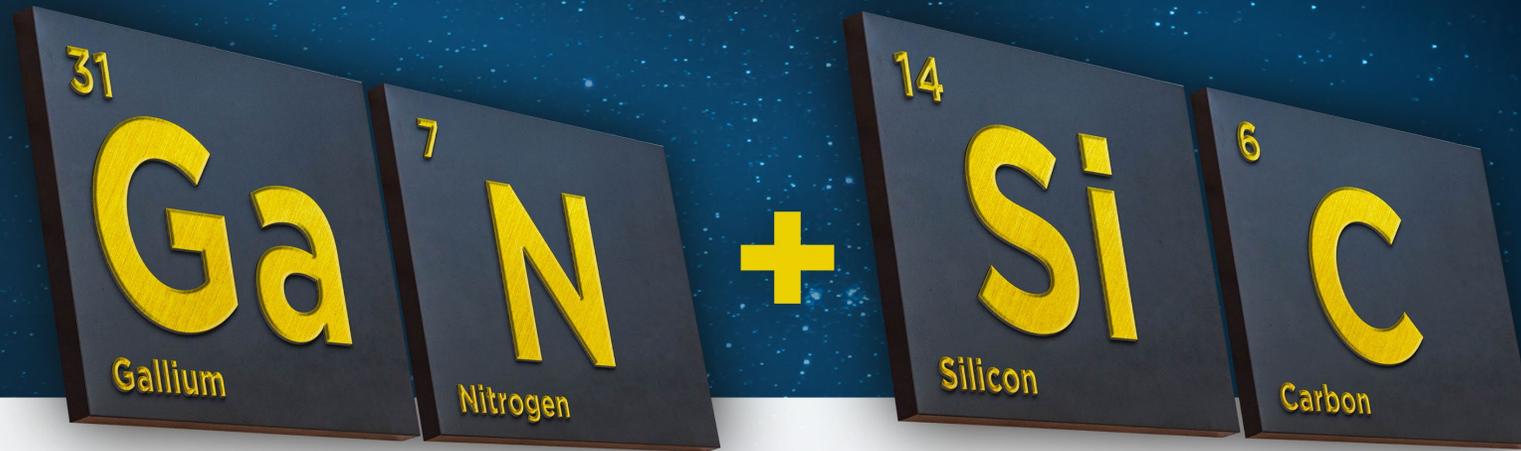
- Nissan Leaf
- Ford F-150 Lightning
- Hyundai Ioniq 5
- Kia EV6
- Mitsubishi Outlander PHEV, etc.

In Context: \$22B 'Pure-Play' Market Opportunity⁽¹⁾



Axes not to scale

1) 2026E potential, Source: Yole, DNV, IRENA, Fraunhofer ISE, IHS, Cisco, Hyperscale, Peer annual reports, Wall Street research.



Pure-Play Next-Gen Power Semiconductors

August 15th, 2022: Navitas Semiconductor, industry-leader in gallium nitride power ICs, acquired GeneSiC Semiconductor, silicon carbide pioneer and industry leader

Navitas: Unique Position in Power Semis



- The only pure-play next-gen power semi company
 - 100% focus on power GaN & SiC (no one else in the world)
 - Leading-edge, industry-leading power GaN & SiC technologies
 - Fastest-growing power GaN & SiC company
- The only semi company certified CarbonNeutral™
 - Highly-efficient carbon footprint; up to 10x lower than Silicon
 - Can address over 2.6 Gtons per year by 2050
- Technology, mgmt team, capability and vision to disrupt \$22B power semiconductor industry...
 - Over 300 years senior mgmt experience in power semis
 - Over 185 patents with most advanced GaN + SiC
 - Capability to impact and accelerate every clean energy segment



Discrete GaN Half-Bridge



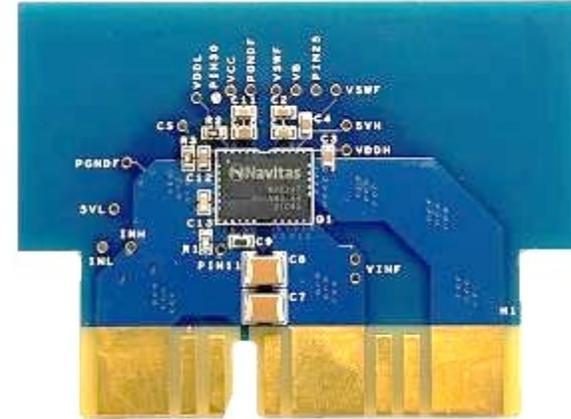
- 33 components
- 250 mm² footprint
- External HB driver HVIC
- External HV bootstrap
- 2x HV bypass diodes
- 2x external gate drives
- Exposed gates

61% fewer components

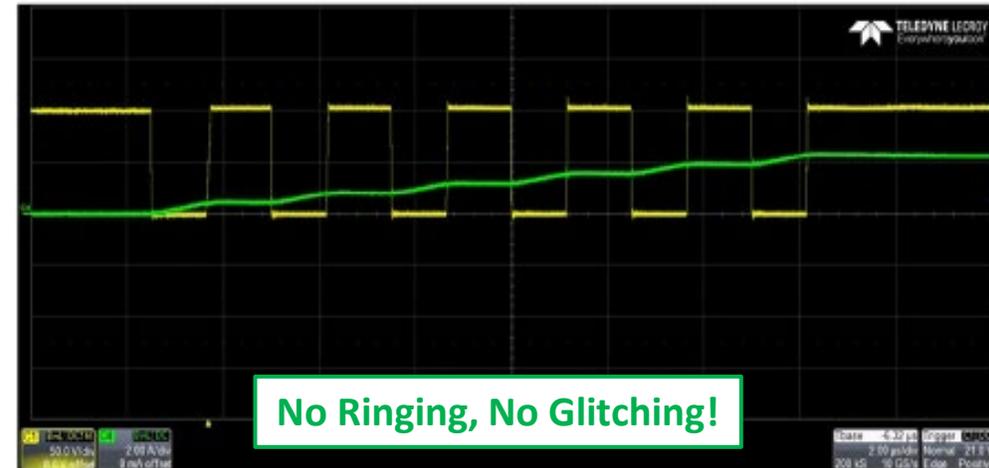
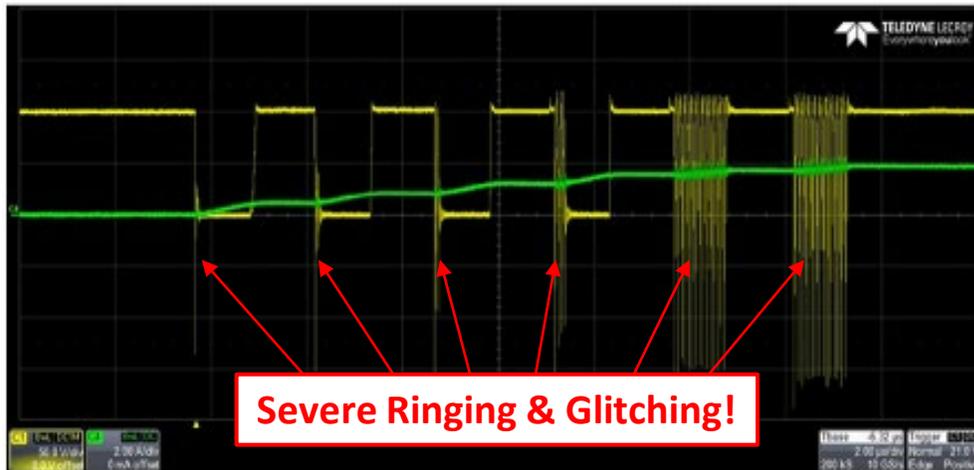
64% smaller footprint

Complete integration

GaNSense Half-Bridge IC



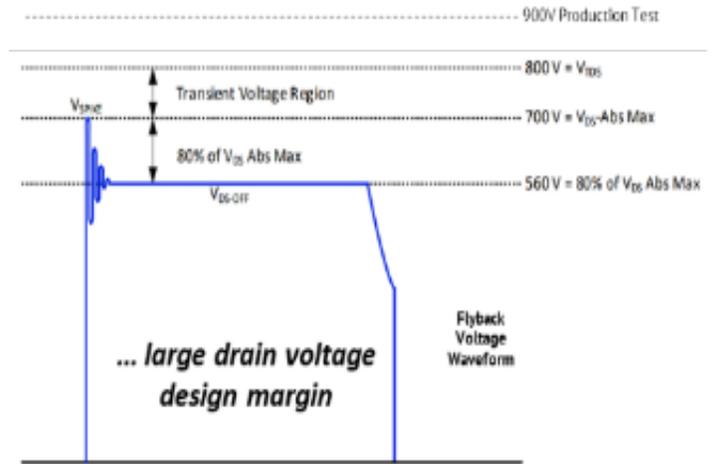
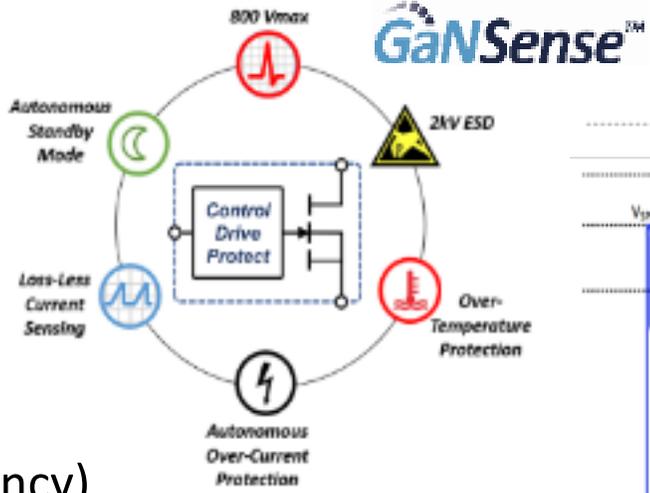
- ✓ 13 components
- ✓ 90 mm² footprint
- ✓ Level shifters
- ✓ Bootstrap
- ✓ Gate drivers
- ✓ No exposed gates



GaN Reliability: Driver Integration is Key



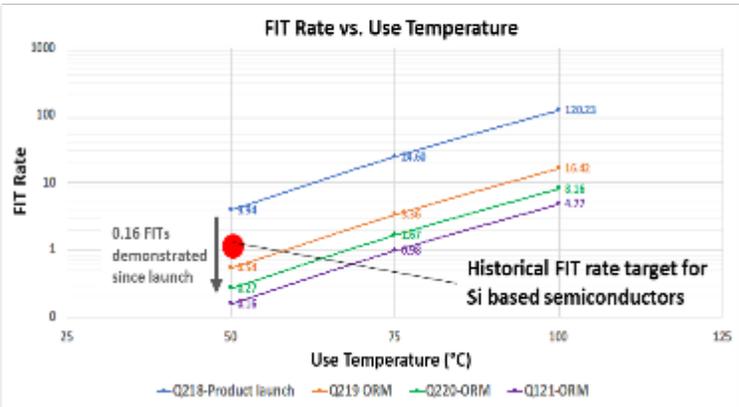
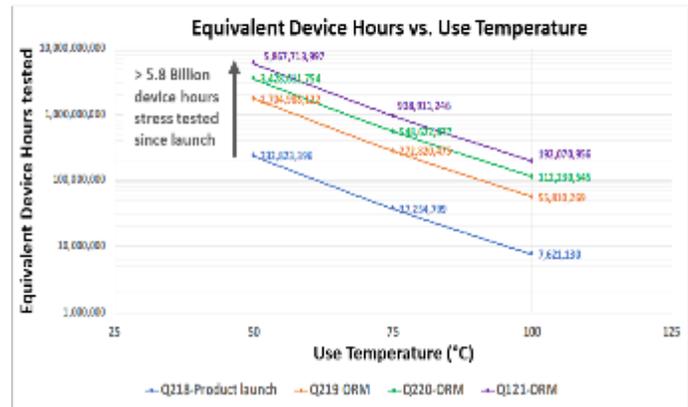
- **Design** for Reliability
 - Integrated drive, sensing and protection
 - Component reliability, and **system** reliability



- **Testing** for Reliability:
 - Proprietary production test methods
 - GaN ICs tested 400% (multi-temp, high-frequency)

- **Characterization** for Reliability
 - Exhaustive, proactive, and unique Navitas reliability program
 - 5.8 B equivalent device hours tested⁽¹⁾
 - Proprietary, highly-accelerated Op-Life, plus JEDEC, plus ELFR monitoring
 - Founder member of JEDEC JC70.1

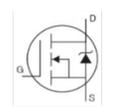
Reliability Statistics
Calculated for High Line condition using HTOL (ZVS) results



(1) As of September 2022
© Navitas Semiconductor 2023

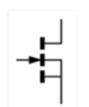
Taking GaN Integration to the Next Level

Silicon FET



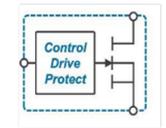
- Old, slow
- $F_{SW} < 100$ kHz

Discrete GaN



- External gate drive
- dV/dt sensitivity
- Layout sensitivity

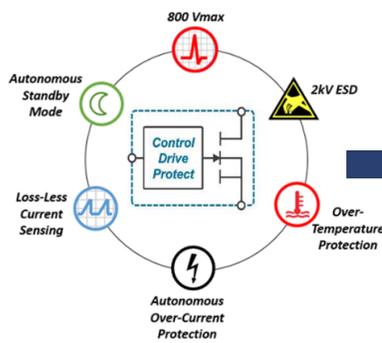
GaNFast™



Power, Drive and Protection

- ✓ Internal Gate
- ✓ Integrated Gate Drive
- ✓ Proven Robustness

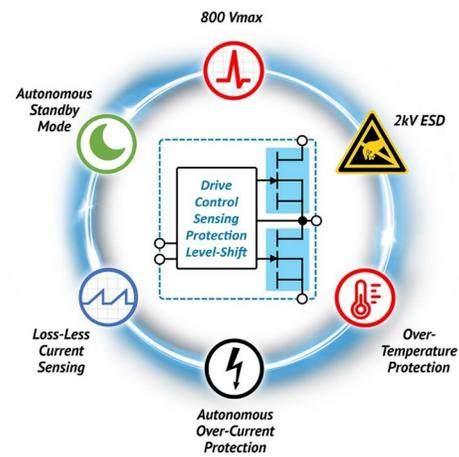
GaNSense™



Sensing, Control

- GaNFast plus:**
- ✓ Autonomous Standby
 - ✓ Autonomous Protection
 - ✓ Loss-less Current Sensing

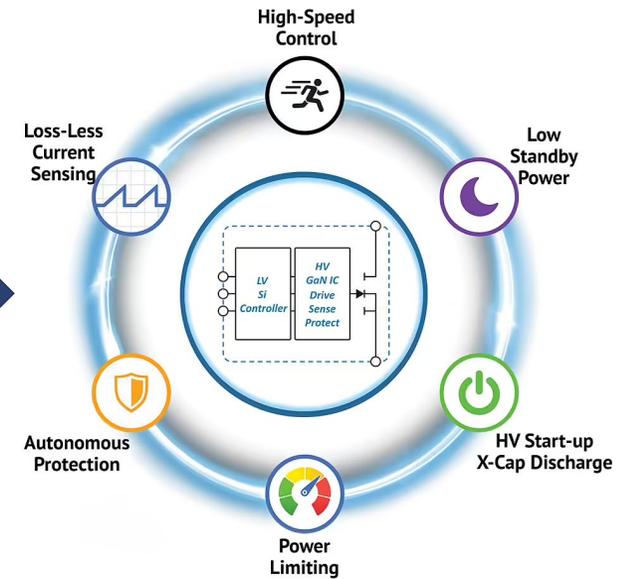
GaNSense Half-Bridge



Full Half-Bridge integration

- GaNSense plus:**
- ✓ Highest integration
 - ✓ integrated HS/LS FETs + isolation

GaNSense Control

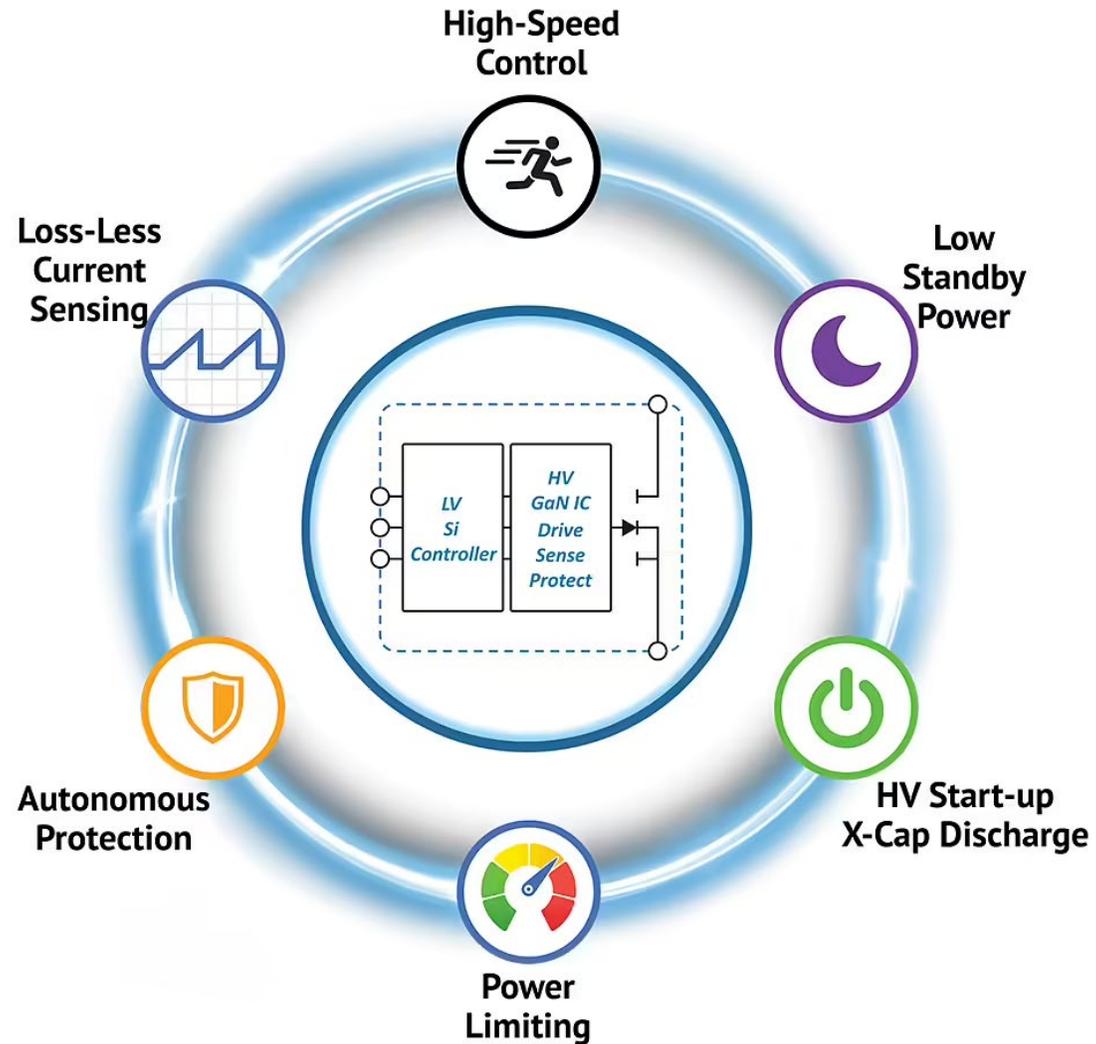


Complete integration of GaNSense + Si Controller

- GaNSense plus:**
- ✓ Integrated HFQR Controller
 - ✓ Fully integrated IC solution



GaNSense™ Control: Ultimate Integration





**75,000,000
Shipped**

Electrify Our World™



Let's go GaNFast™



Up to 6.5 kV

Largest range of SiC FETs & diodes
(650 V to 6.5 kV)

Fast Switching

Highest efficiency hard-switch, soft-switch
(Lowest E_{ON} , E_{OFF} , E_{ZVS} losses)

Cool Operation

Lowest $R_{DS(ON)}$ at high temperature
(25% lower than industry typical)

100%-Tested Robust Avalanche

Highest published capability to handle excess energy in fault condition

Long Short-Circuit Withstand Time

World-class survival duration in fault condition

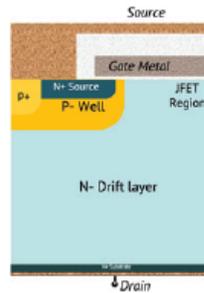
High-Power Paralleling

Matching currents
(Stable V_{TH})



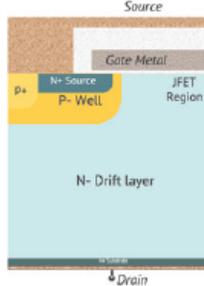
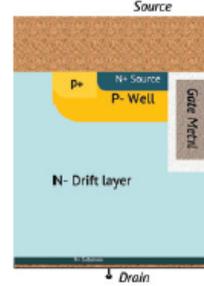
The Planar Problem

Planar



Manufacturability	<ul style="list-style-type: none">» <i>Repeatable</i>» <i>High yield</i>» <i>Low cost</i>
Performance	<ul style="list-style-type: none">» <i>High $R_{DS(ON)}$ / area</i>» <i>Slow switching</i>» <i>High $R_{DS(ON)}$ / Δ temp</i>
Reliability	<ul style="list-style-type: none">» <i>Rugged gate oxide (stable V_{TH})</i>

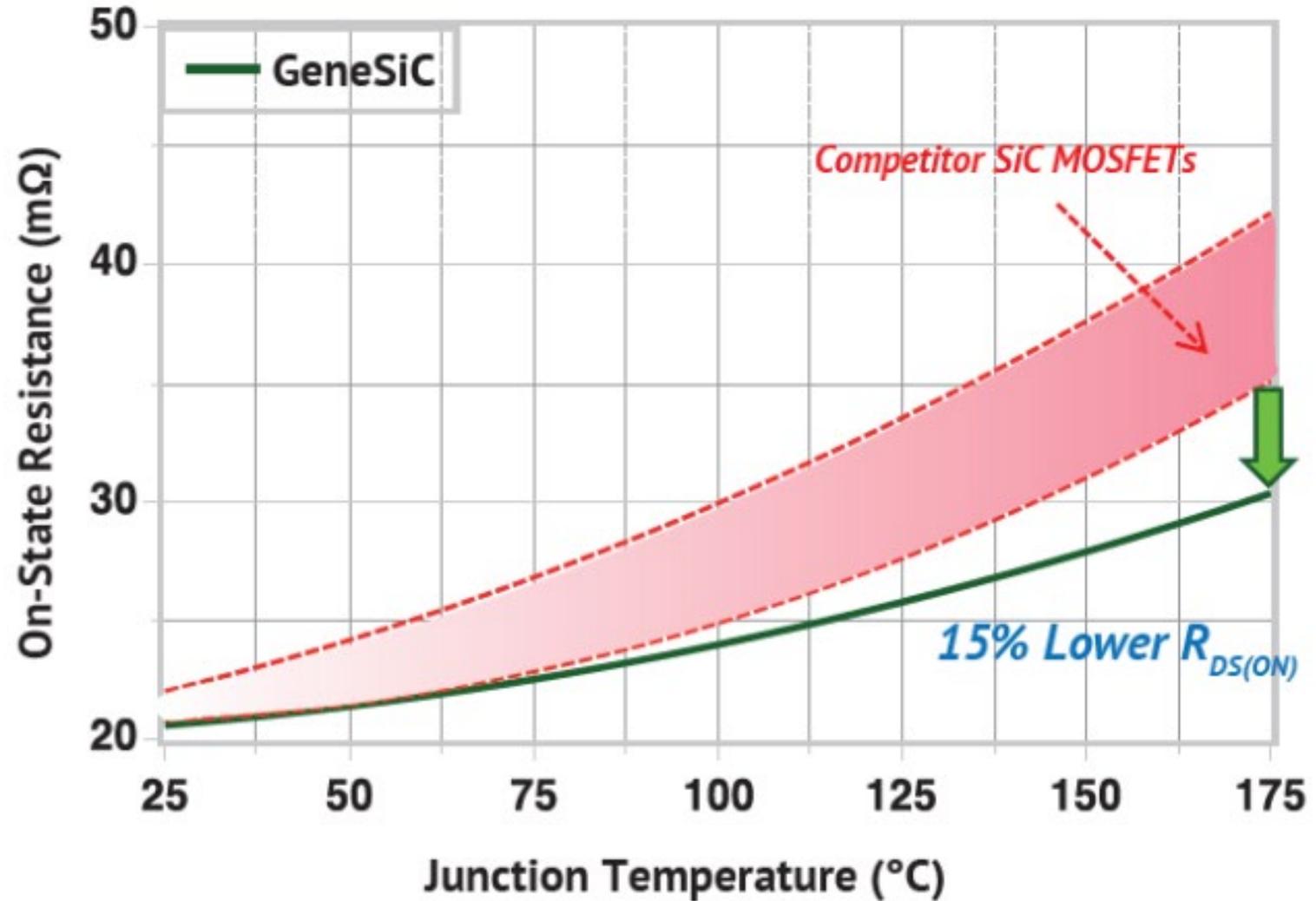
The Trouble with Trench

	<p>Planar</p> 	<p>Trench</p> 
Manufacturability	<ul style="list-style-type: none"> » Repeatable » High yield » Low cost 	<ul style="list-style-type: none"> » Inconsistent trench etch » Lower yields » High cost
Performance	<ul style="list-style-type: none"> » High $R_{DS(ON)}$ / area » Slow switching » High $R_{DS(ON)}$ / Δ temp 	<ul style="list-style-type: none"> » Lower $R_{DS(ON)}$ / area » Faster switching » High $R_{DS(ON)}$ / Δ temp
Reliability	<ul style="list-style-type: none"> » Rugged gate oxide (stable V_{TH}) 	<ul style="list-style-type: none"> » Failures due to non-uniform gate oxide » Lower short-circuit capability

Best of Both: Trench-Assisted Planar Gate

	<p>Planar</p>	<p>Trench</p>	<p>GeneSiC</p>
Manufacturability	<ul style="list-style-type: none"> » Repeatable » High yield » Low cost 	<ul style="list-style-type: none"> » Inconsistent trench etch » Lower yields » High cost 	<ul style="list-style-type: none"> » Repeatable » High yield » Low cost
Performance	<ul style="list-style-type: none"> » High $R_{DS(ON)}$ / area » Slow switching » High $R_{DS(ON)}$ / Δ temp 	<ul style="list-style-type: none"> » Lower $R_{DS(ON)}$ / area » Faster switching » High $R_{DS(ON)}$ / Δ temp 	<ul style="list-style-type: none"> » Lower $R_{DS(ON)}$ / area » Fastest switching » Lowest $R_{DS(ON)}$ / Δ temp
Reliability	<ul style="list-style-type: none"> » Rugged gate oxide (stable V_{TH}) 	<ul style="list-style-type: none"> » Failures due to non-uniform gate oxide » Lower short-circuit capability 	<ul style="list-style-type: none"> » Highest 100% tested avalanche » Long short-circuit withstand time » Rugged gate oxide (stable V_{TH})

Efficient at High Temperatures



Best High-Speed, High-Temp Performance

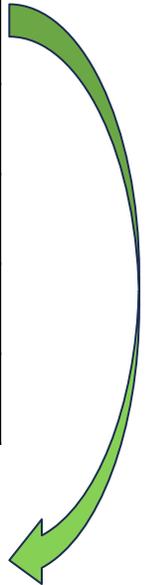


Supplier	Resistance		Energy Loss				Figure-of-Merit <i>(Low number is better)</i>	
	$R_{DS(ON)}$ @ 25°C (mΩ)	$R_{DS(ON)}$ @ 175°C (mΩ)	E_{ON} @ 25A (μ)	E_{OFF} @ 35A (μ)	E_{OSS} @ 800V (μ)	E_{ZVS} $E_{OFF}-E_{OSS}$ (μ)	Hard-Switching $R_{DS} @ 175°C \times (E_{ON}+E_{OFF})$ (Ω-μ)	Soft-Switching $R_{DS} @ 175°C \times E_{ZVS}$ (Ω-μ)
GeneSiC	40	57	600	80	34	46	38.8	2.6
#2	40	68	600	80	40	40	46.2	2.7
#3	40	80	850	390	35	355	99.2	28.4
#4	40	71	550	150	35	115	49.7	8.2
#5	45	85	520	65	29	36	49.7	3.1

Lowest power loss at high temp, high speed

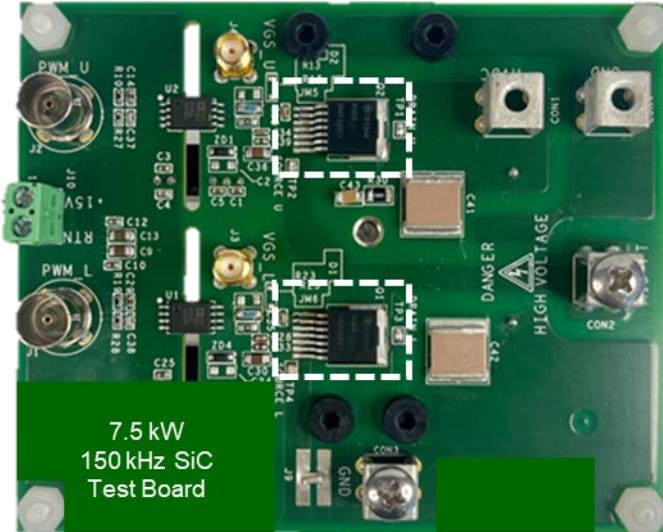
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**Highest Efficiency, Energy Savings
Small Size, Light Weight, Low System Costs!**



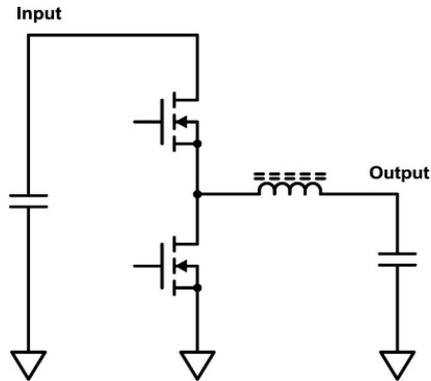
Reference 1,200V SiC FET, 40-45mΩ devices; GeneSiC = Trench-Assisted Planar G3R40MT12J; based on Navitas test result & competitive data sheet parameters.

Faster, Cooler, Longer Lifetime

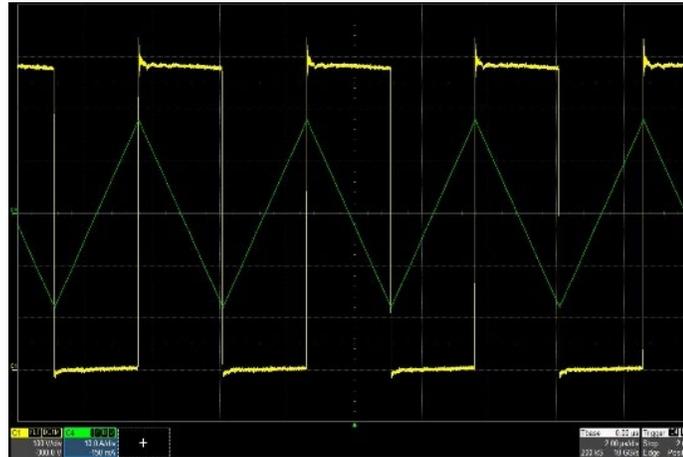


Test Board

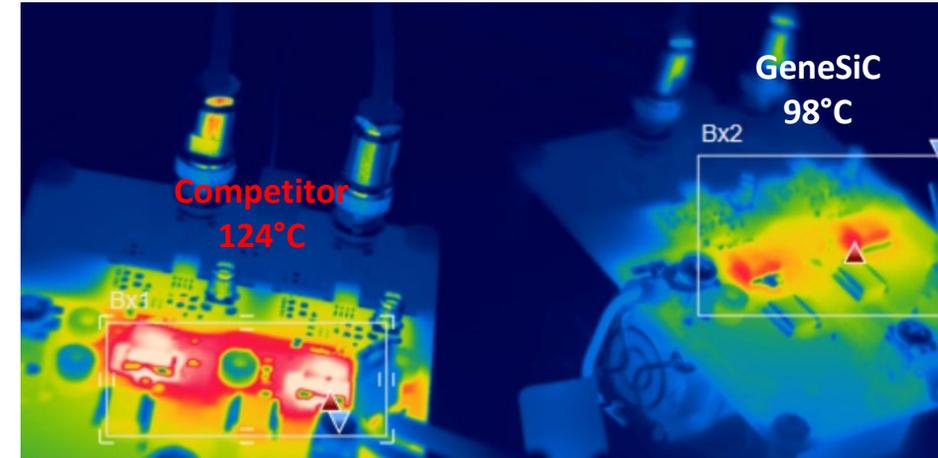
- GeneSiC trench-assisted planar FET vs. Competitor SiC FET
 - 1,200 V, 40 mΩ, D2pak in half-bridge
 - Represents 7.5 kW DC-DC converter (e.g. data center, EV)
 - 150 kHz switching = ~10x faster than Si IGBT example
- GeneSiC: **>80% energy savings (>3,000 kWh/yr) vs Si IGBTs**
-25°C cooler = 3x longer life vs other SiC
(reduced maintenance / repair costs)



Test Circuit
(1-phase of 3-phase motor drive)



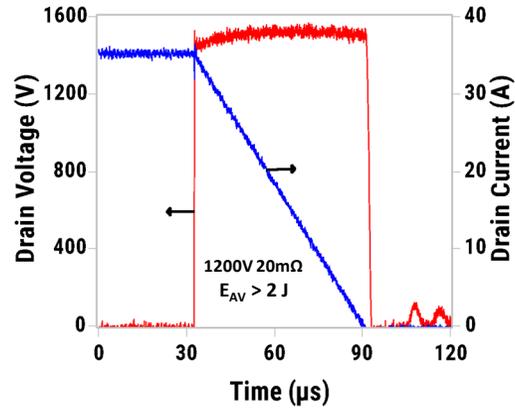
Switching Waveforms
(40 A pk-pk, 20 A turn-off)



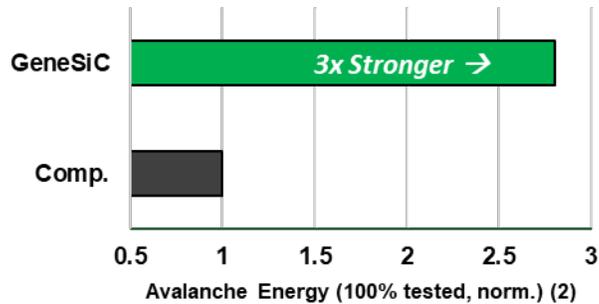
Thermal Camera

100%-Tested Avalanche

Highest published capability to handle excess energy in fault condition

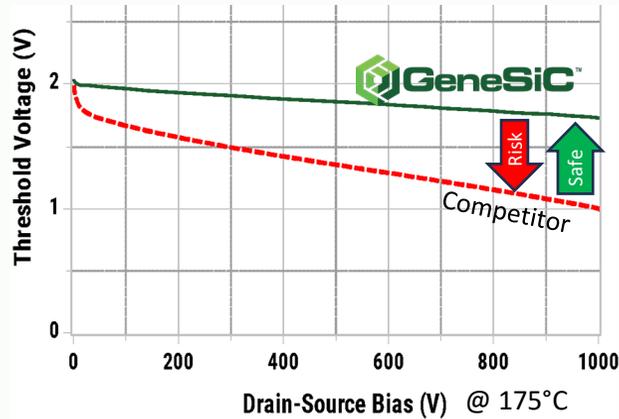


Critical in applications like motor drives to withstand unclamped inductive load (UIL) energy dump in situations like motor open-circuit (O.C.)



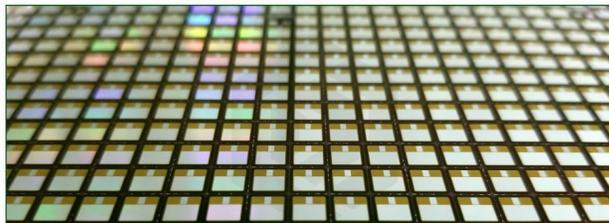
High Power Paralleling

Matching currents
(Stable V_{TH})



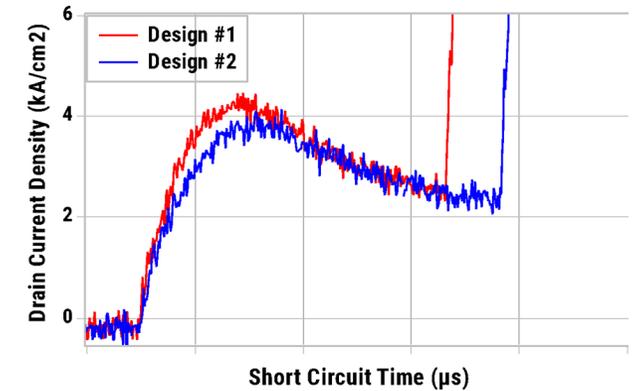
Competitor products allow threshold voltage to drop under high voltage, creating risk of turn-on error

GeneSiC packaged and bare-die FETs can be paralleled reliably for high-power applications

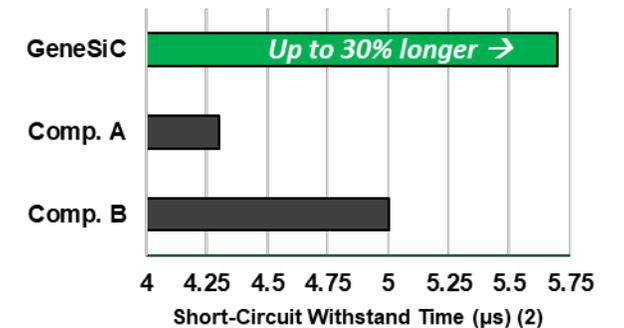


Long Short-Circuit Withstand Time

World-class survival duration
in fault condition

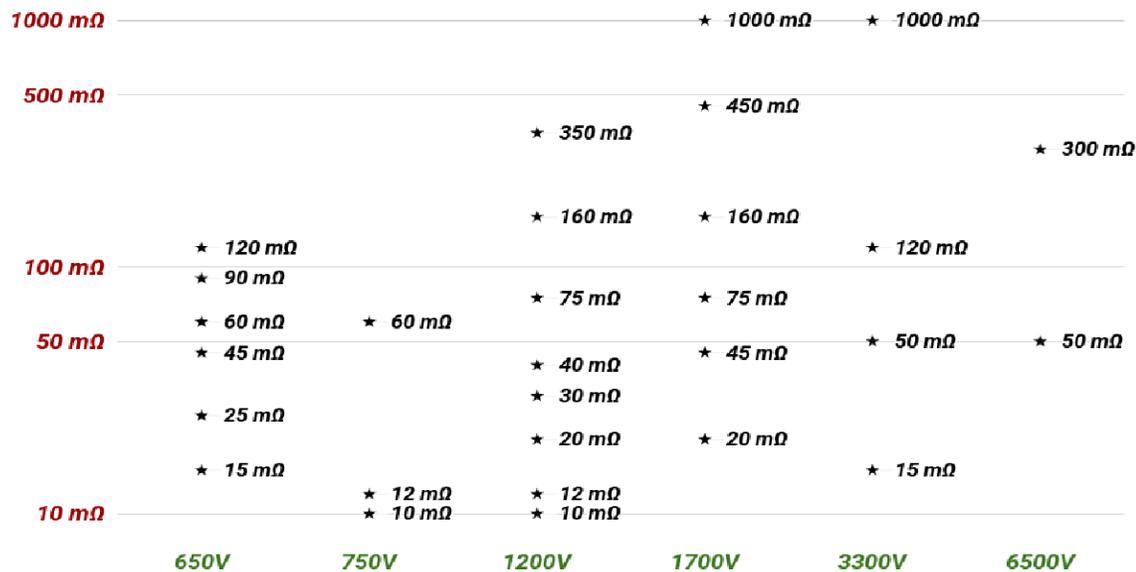


Critical to prevent failures like motor short circuit where the FET faces full voltage (V_{DD}) in ON-state.

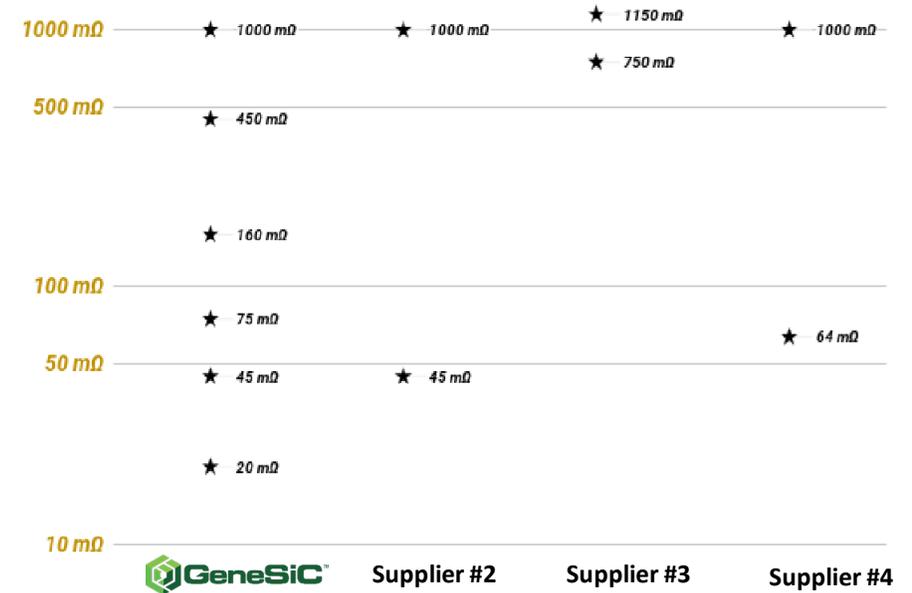


Broadest SiC FET Portfolio⁽¹⁾

GeneSiC™ 650–6,500V Trench-Assisted Planar SiC FETs



GeneSiC™ Most 1,700V SiC FETs



- 50+ SiC MOSFETs, array of standard packages
- Only supplier with 650V to 6,500V SiC MOSFETs

- Broadest industry offering for 1700V SiC MOSFETs

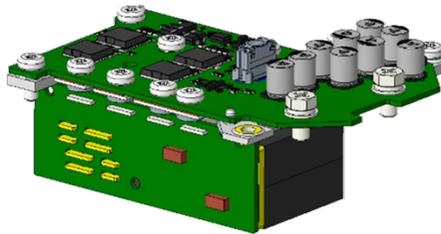


1) based on GeneSiC voltage range of production released SiC MOSFETs compared to all publicly identified voltage ranges of other SiC suppliers.

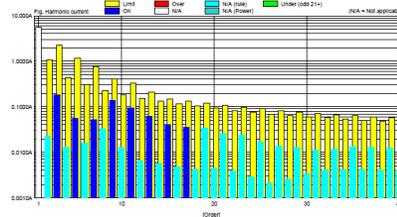
Develop *prototype* data center power supplies & EV powertrain systems, Improve component performance, and establish industry-best benchmarks

Systems

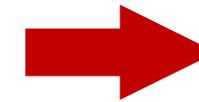
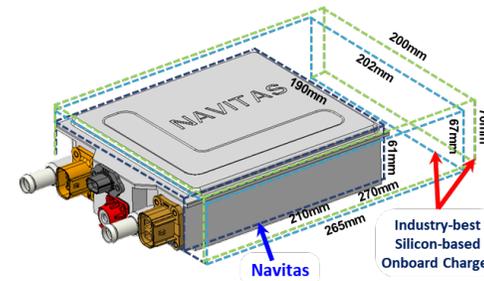
Design for Hi- F_{SW} , Hi-Efficiency, Low-Cost



Testing to enable accelerated Design-IN



Design-IN assistance for key customers



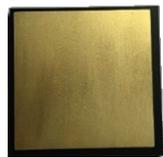
Customer



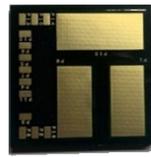
Revenue Ramp

Components

Products & Packages design feedback

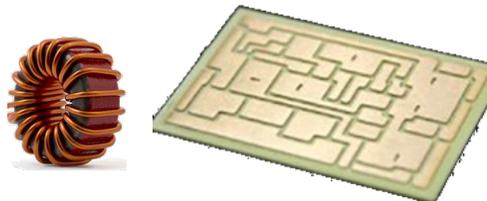


Top

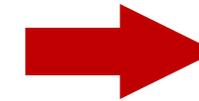
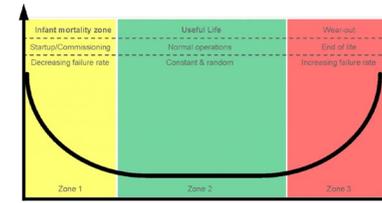


Bottom

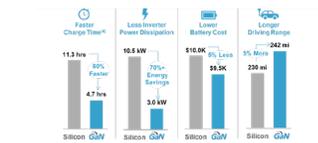
Enable low-cost, quality Ecosystem



Lifetime Reliability system-level testing



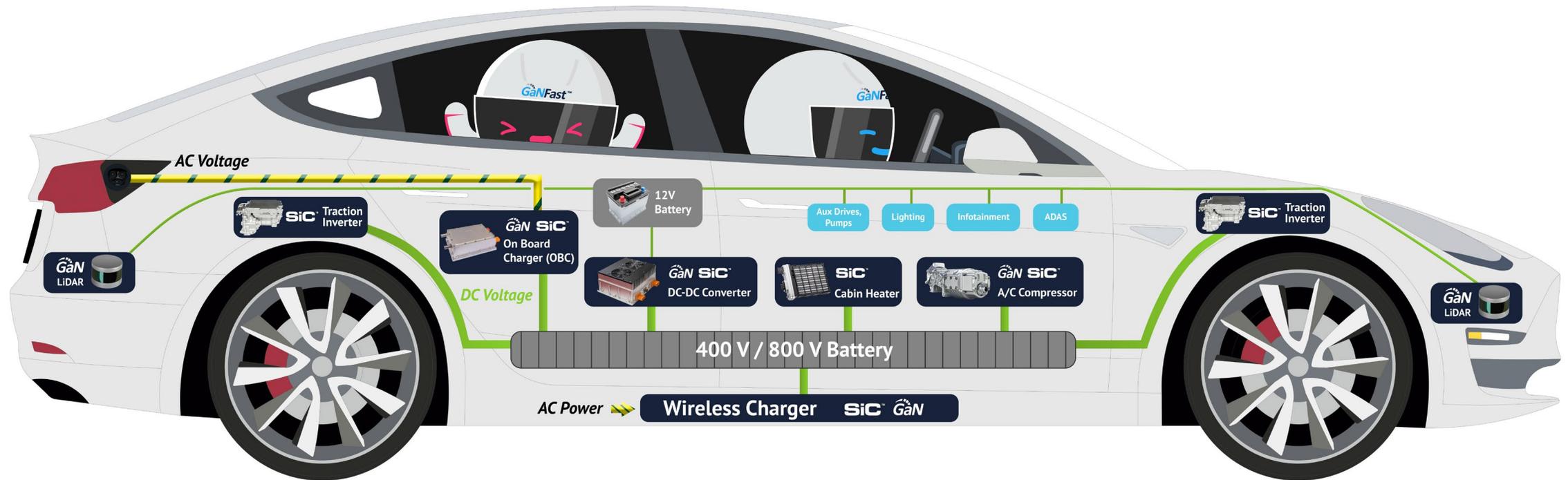
Establish



Benchmarks

\$12B/yr Potential for GaN/SiC by 2030⁽¹⁾

- ✓ OBC > \$38
 - ✓ DC-DC > \$12
 - Traction drive >\$286
 - **Total:** >\$330 per EV = \$10.1B
- ...and >\$1.9B in road-side chargers**



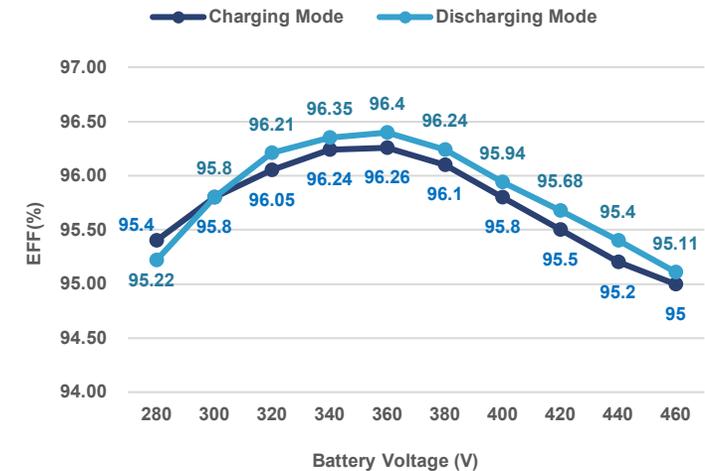
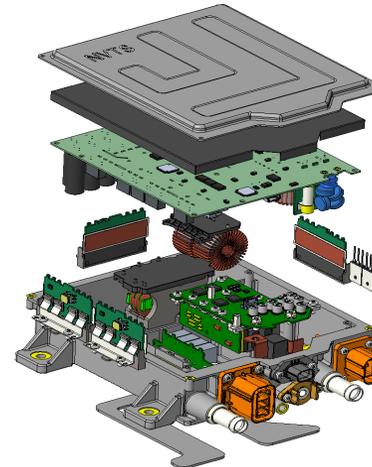
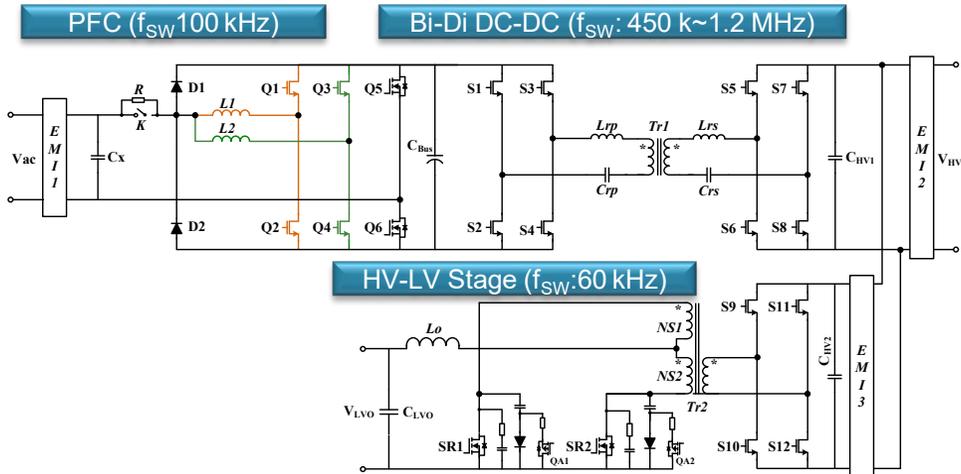
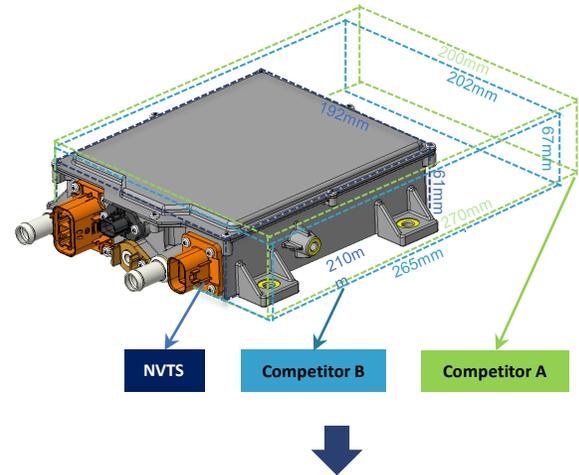
Note: Assumes 150 kW traction inverter, 100 kWh battery, \$100/kWh battery cost and typical 230 mile range.

(1) Estimate 2030, 30M EV/yr, based on DNV and Navitas analysis
(2) Based on BCG Research, Yole Research and Navitas analysis.

6.6kW OBC/LDC Combo (GaN only & GaN/SiC)

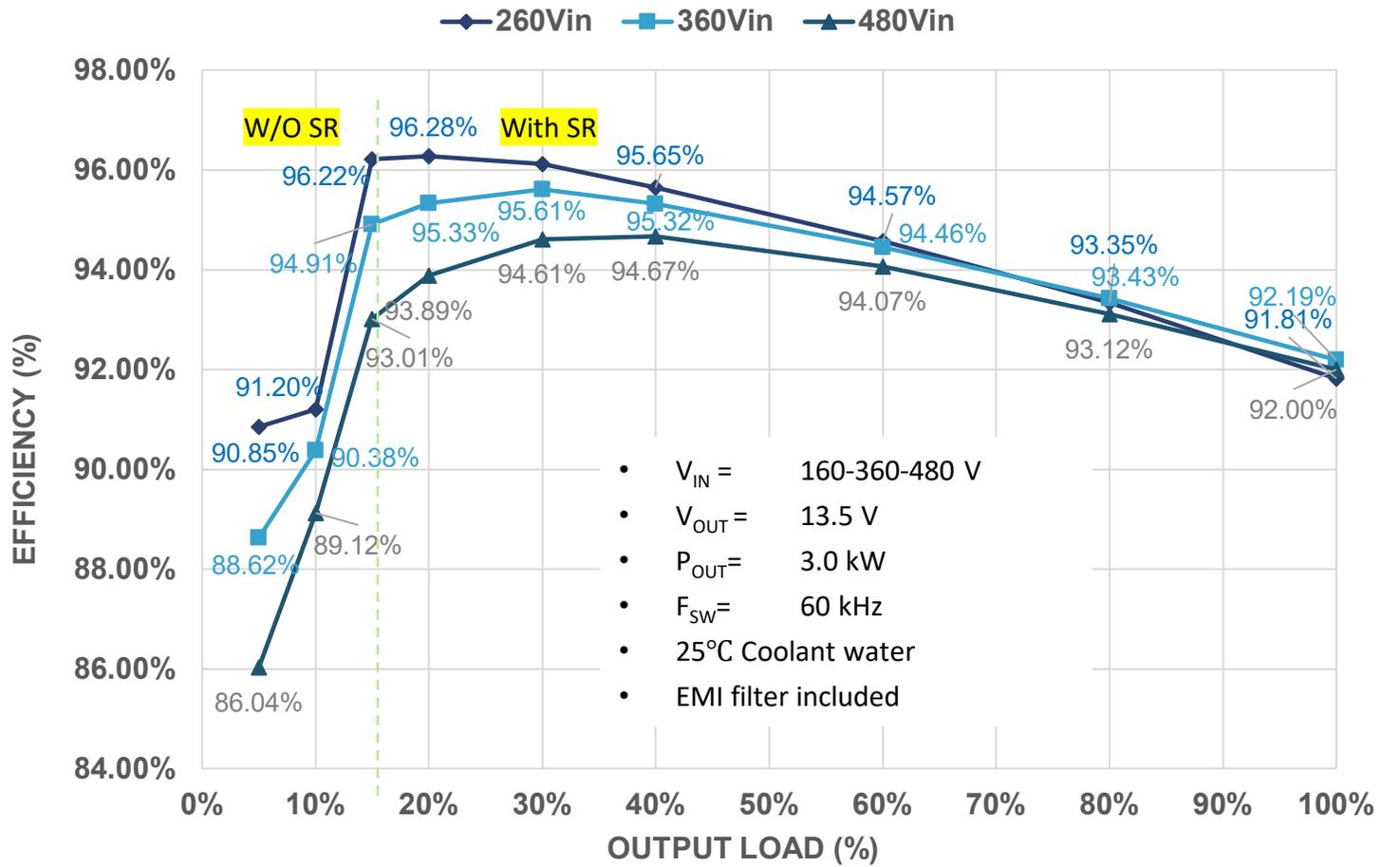
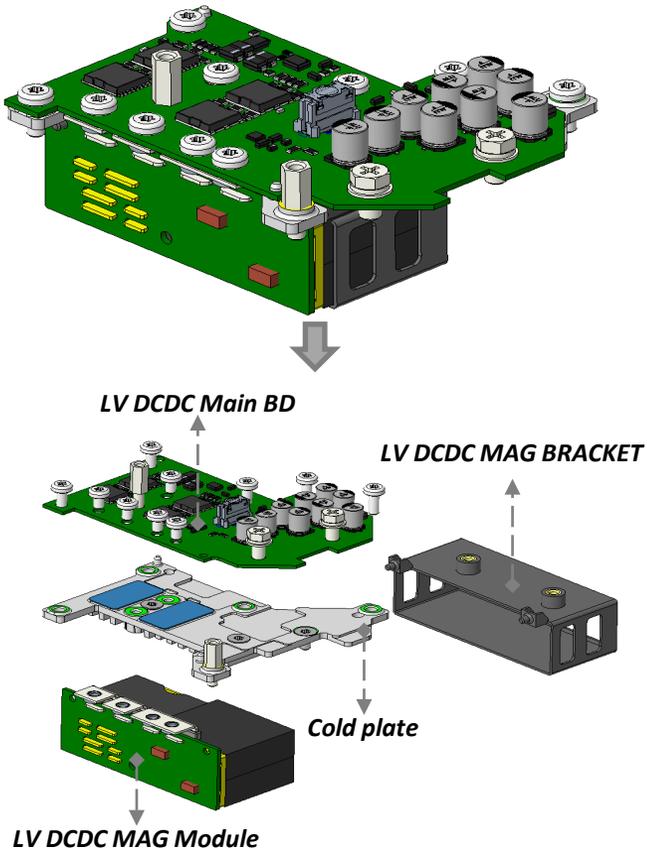
• GaN/GaN+SiC based 6.6 kW OBC+3.0 kW DC-DC Combo

- ✓ Bi-6.6 kW OBC
- AC Voltage: 90 ~ 265 V_{AC} / up to 32 A
- DC Voltage: **470~860 V, 500~860 V full load**
- Power: 6.6 kW charge, 6.0 kVA discharge
- Efficiency : > 95.0% @ full load
- ✓ 3.0 kW DC-DC
- LV DC Voltage: 9~16 V
- ✓ Dimension: 210 x 192 x 61 mm (<2.5 L)
- ✓ Cooling: -40~65 °C liquid-cooled
- ✓ Others: IP 67, CAN interface

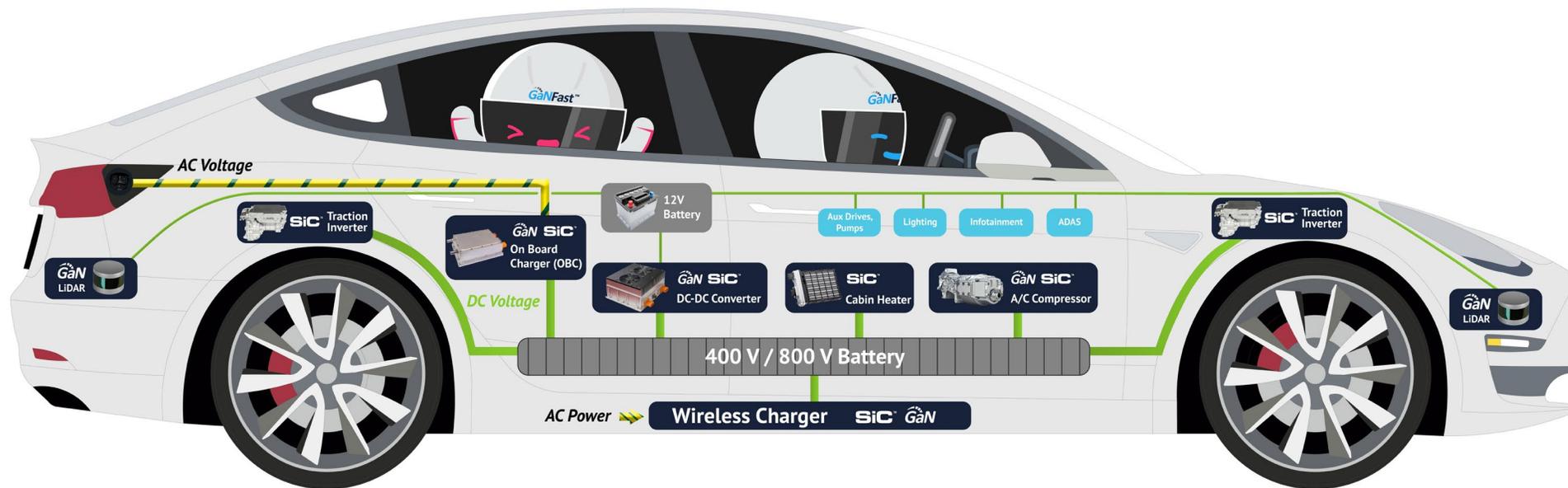


3 kW LDC Efficiency

- Exploded 3D View of LV DC-DC Assembly



- **Level-3 ultra-fast chargers, up to 350 kW**
- **New architectures increased working bus voltage from 1,000 to 1,500V**
 - **Increase power density**
 - **Simplify designs**
 - **Improve efficiency, reliability and system cost**
- **1,500V bus needs up to 3,300V SiC device capability, to cover main and auxiliary power**



“10-80% charge in only 18 minutes!”⁽¹⁾



ZEEKR



ZEEKR VREMT - Navitas Semiconductor

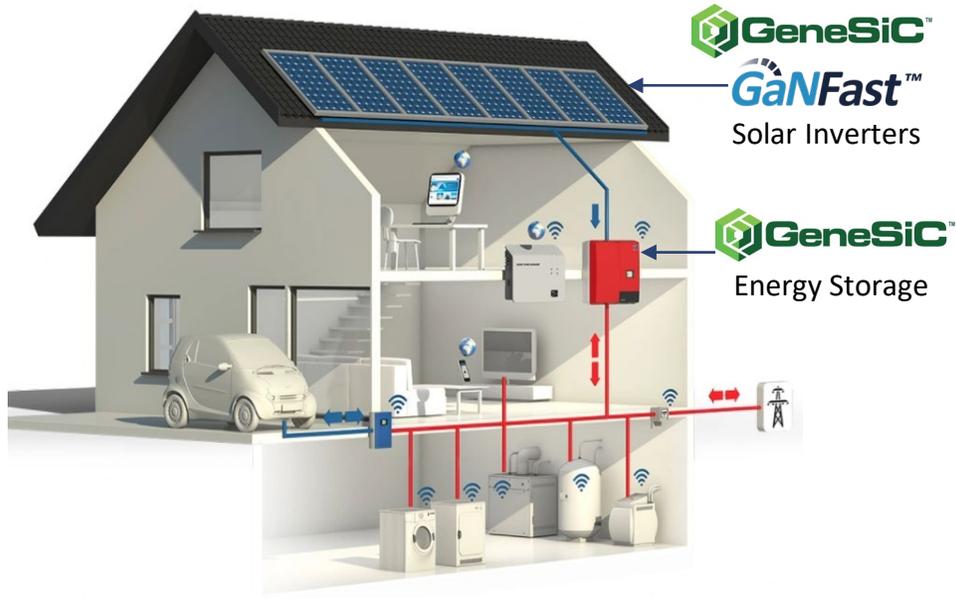
Next-Generation Power Semiconductor Joint Lab



Navitas



GaN + SiC for Solar & Energy Storage



25°C cooler with GeneSiC

20 Customers in Development, Production



Market Potential (2)

- Residential Micro >\$1.4B (GaN)
- Residential String >\$1.0B (SiC)
- Commercial String >\$1.0B (SiC)
- Energy Storage >\$1.25B (SiC) (50% attach rate)

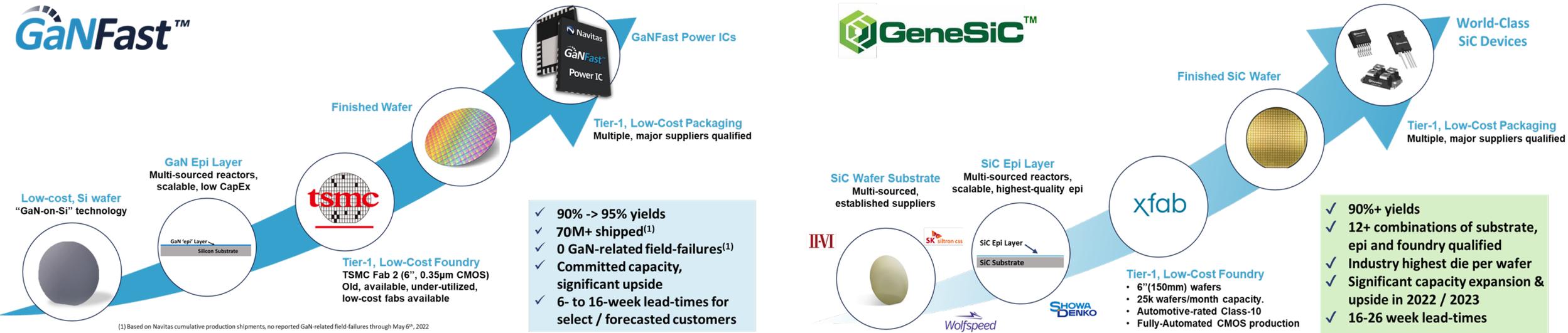
Total = >\$4.65B

Navitas Strength & Opportunities

- Solar up 3x 2022-2027, more capacity than natural gas by 2026, coal by 2027
- Inflation Reduction Act: >\$50B to solar, storage and wind
- Bus voltages rising to 1,500V – matches GeneSiC 3,300V capability

(1) Navitas est. 6.2 kW residential installation with silicon inverter at 97.5%, GaN at 98.5% efficiency.
 (2) Market estimates for 2030, based on DNV and Navitas analysis

High Capacity, 50% Shorter Lead-times⁽¹⁾



- Tier-1 foundry partners, excellent manufacturing support
- High yields, low costs, flexible supply chains
- Long-term capacity agreements: GaN up 3x, SiC up 5x starting in 2023
- 50% shorter lead-times than industry typical

1) Industry lead-times per Jefferies Equity Research, August '22
© Navitas Semiconductor 2023

Leader in Sustainability: 150,000+ tons CO₂ Saved! ⁽¹⁾



February '22 First GaN sustainability report based on global standards.

Every **GaNFast™ IC**
saves
4 kg CO₂



4x-10x lower component CO₂ footprint than silicon

28% lower lifetime CO₂ footprint for chargers / adapters

Accelerates transition from ICE to EV by **3 years**, saving **20%/yr** of road-sector emissions by 2050

GaN + SiC save up to **6 Gton / year** by 2050



May '22 World's first semiconductor company CarbonNeutral® certified

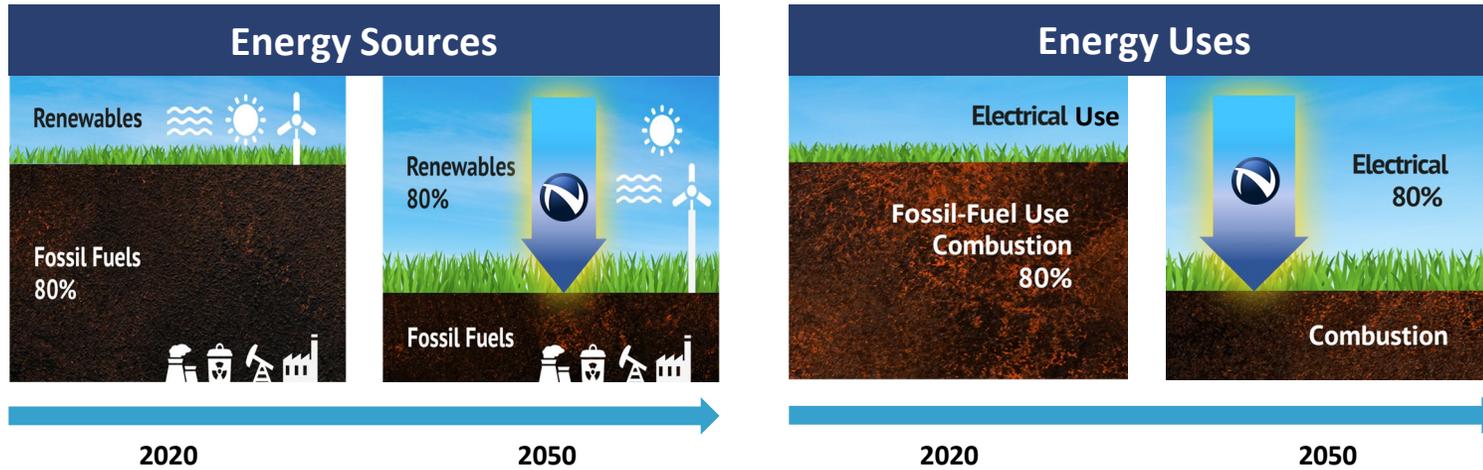


August '22 First 100,000 tons CO₂ saved

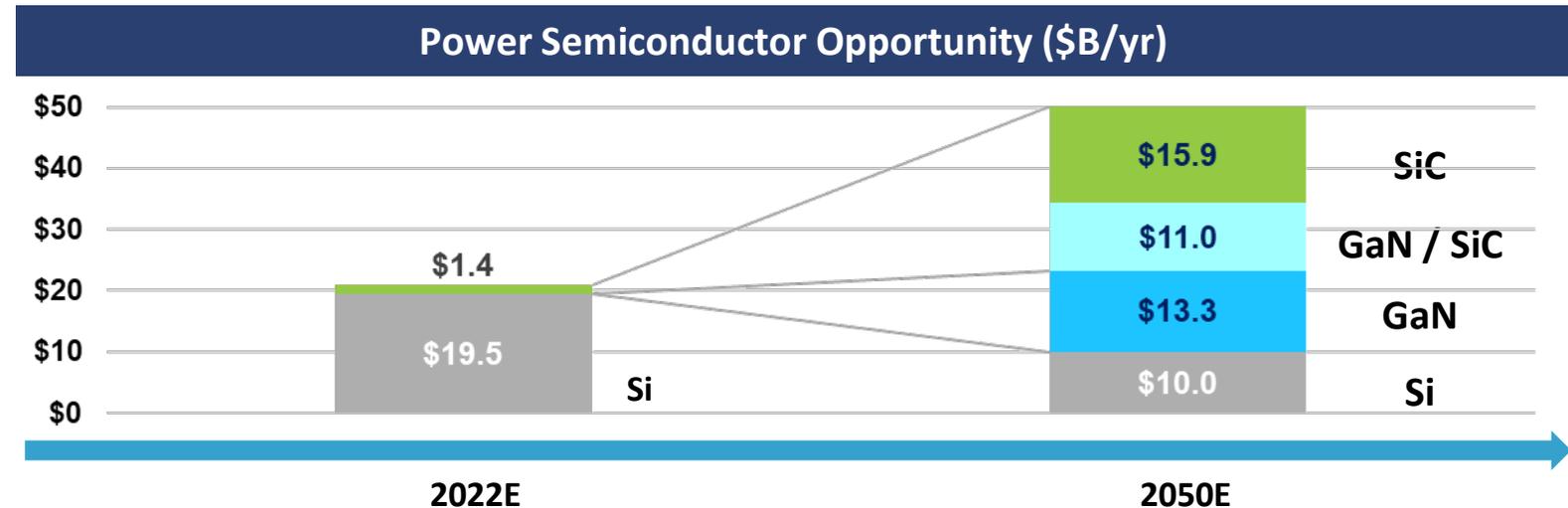


October '22 Recognized for industry-leading sustainability reporting

Energy sources and uses are being electrified...



...creating a **\$40B GaN + SiC opportunity by 2050**



Fossil-fuel vs renewable ratios adapted from IRENA 2020 "Global Renewables Outlook".
Shift required to meet "Transforming Energy Scenario, 9.5 Gton target in 2050", per Paris Agreement's 1.5°C rise.
Market opportunity \$ from Yole Développement, 2020 and Navitas analysis.

Electrify Our World™

From:

20 W Mobile fast-chargers to

20 kW EV on-board chargers to

20 MW Grid-tied systems

Navitas GaNFast power ICs and GeneSiC power FETs and diodes drive efficiency, power density and lower system costs

Faster Acceleration Longer Range More Power Faster Charging



Smaller Lighter Higher Density Higher Efficiency

